

Appl. No.: 09/832,884
Amdt. Dated: November 10, 2003
Reply to Office Action of: September 10, 2003

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application:

1. (currently amended) An end use device having a known good die (KGD), the KGD having ~~optional~~ solder ball array and ~~or~~ wire bond connections;

the KGD having solder ball array connections on ~~the~~ a planar KGD ~~known good die~~ surface;

the KGD having an array of wire bond connections on the KGD planar surface ~~die electrically connected to the solder ball array connections;~~

the KGD having electrical connections between all of the solder ball array connections and the wire bond connections;

wherein the KGD ~~known good die~~ is a KGD which is thermal stress tolerance tested prior to mounting the KGD ~~known good die~~ on the end use device by a test device connected to the KGD ~~known good die~~ by the wire bond connections or in the alternative by the solder ball connections;

wherein when either the wire bond connections are used or the solder ball connections are used for a ~~the~~ known good die test, the other connections are connected to the end use ~~us~~ device; and

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the connections used for the known good die test are not connected to the end use device or any other device, when the KGD ~~known good die~~ is ~~placed in~~ connected to the end use device.

2. (currently amended) The end use device in accordance with claim 1, wherein when either the wire bond connections or ~~stress tolerant~~ solder ball connections is used for the known good die test to form contact with the test device, the other is not affected by the a known good die (KGD) test and remains pristine until connected to the end use device.

3. (previously presented) The end use device in accordance with claim 1, wherein the wire bond connections and the solder ball array connections are on the same side of the die.

4. (canceled)

5. (previously presented) The end use device in accordance with claim 1, wherein the solder ball array connections or wire bond connections which are used when the die is tested are not removed from the die.

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6. (previously presented) The end use device in accordance with claim 1, wherein connections to the test device are metallurgical connections.

7. (previously presented) The end use device in accordance with claim 1, wherein the solder ball array connections are controlled collapse chip connections.

8 - 10. (canceled)

44. (canceled)